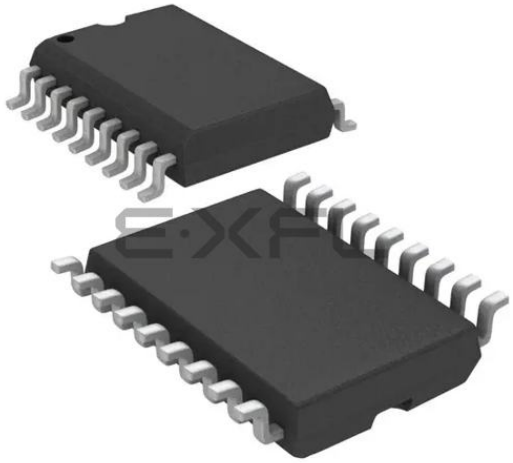

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc558t-04i-so

TABLE 1-1: PIC16C55X FAMILY OF DEVICES

		PIC16C554	PIC16C557	PIC16C558
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	2K	2K
	Data Memory (bytes)	80	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0
Features	Interrupt Sources	3	3	3
	I/O Pins	13	22	13
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5
	Brown-out Reset	—	—	—
	Packages	18-pin DIP, SOIC; 20-pin SSOP	28-pin DIP, SOIC; 28-pin SSOP	18-pin DIP, SOIC, SSOP
All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C55X Family devices use serial programming with clock pin RB6 and data pin RB7.				

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TABLE 3-1: PIC16C55X PINOUT DESCRIPTION

Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	SOIC	SSOP			
OSC1/CLKIN	16	16	18	I	ST/CMOS	Oscillator crystal input/external clock source output.
OSC2/CLKOUT	15	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	4	4	4	I/P	ST	Master clear (Reset) input/programming voltage input. This pin is an active low RESET to the device.
RA0	17	17	19	I/O	ST	Bi-directional I/O port
RA1	18	18	20	I/O	ST	Bi-directional I/O port
RA2	1	1	1	I/O	ST	Bi-directional I/O port
RA3	2	2	2	I/O	ST	Bi-directional I/O port
RA4/T0CKI	3	3	3	I/O	ST	Bi-directional I/O port or external clock input for TMR0. Output is open drain type.
RB0/INT	6	6	7	I/O	TTL/ST(1)	Bi-directional I/O port can be software programmed for internal weak pull-up. RB0/INT can also be selected as an external interrupt pin.
RB1	7	7	8	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB2	8	8	9	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB3	9	9	10	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB4	10	10	11	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin.
RB5	11	11	12	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin.
RB6	12	12	13	I/O	TTL/ST(2)	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin. Serial programming clock.
RB7	13	13	14	I/O	TTL/ST(2)	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin. Serial programming data.
RC0(3)	18	18	18	I/O	TTL	Bi-directional I/O port input buffer.
RC1(3)	19	19	19	I/O	TTL	Bi-directional I/O port input buffer.
RC2(3)	20	20	20	I/O	TTL	Bi-directional I/O port input buffer.
RC3(3)	21	21	21	I/O	TTL	Bi-directional I/O port input buffer.
RC4(3)	22	22	22	I/O	TTL	Bi-directional I/O port input buffer.
RC5(3)	23	23	23	I/O	TTL	Bi-directional I/O port input buffer.
RC6(3)	24	24	24	I/O	TTL	Bi-directional I/O port input buffer.
RC7(3)	25	25	25	I/O	TTL	Bi-directional I/O port input buffer.
VSS	5	5	5,6	P	—	Ground reference for logic and I/O pins.
VDD	14	14	15,16	P	—	Positive supply for logic and I/O pins.

Legend: O = Output, I/O = Input/output, P = Power, — = Not used, I = Input, ST = Schmitt Trigger input, TTL = TTL input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: PIC16C557 only.

4.2.2.2 OPTION Register

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0 and the weak pull-ups on PORTB.

Note 1: To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT (PSA = 1).

REGISTER 4-2: OPTION REGISTER (ADDRESS 81H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							bit0

bit 7 **$\overline{\text{RBPU}}$**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6 **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5 **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4 **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3 **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

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4.2.2.4 PCON Register

The PCON register contains a flag bit to differentiate between a Power-on Reset, an external $\overline{MCLR}$ Reset or WDT Reset. See Section 6.3 and Section 6.4 for detailed RESET operation.

REGISTER 4-4: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—	—	—	—	—	—	$\overline{POR}$	—
bit7							bit0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **$\overline{POR}$**: Power-on Reset status bit
1 = No Power-on Reset occurred
0 = Power-on Reset occurred

bit 0 **Unimplemented:** Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

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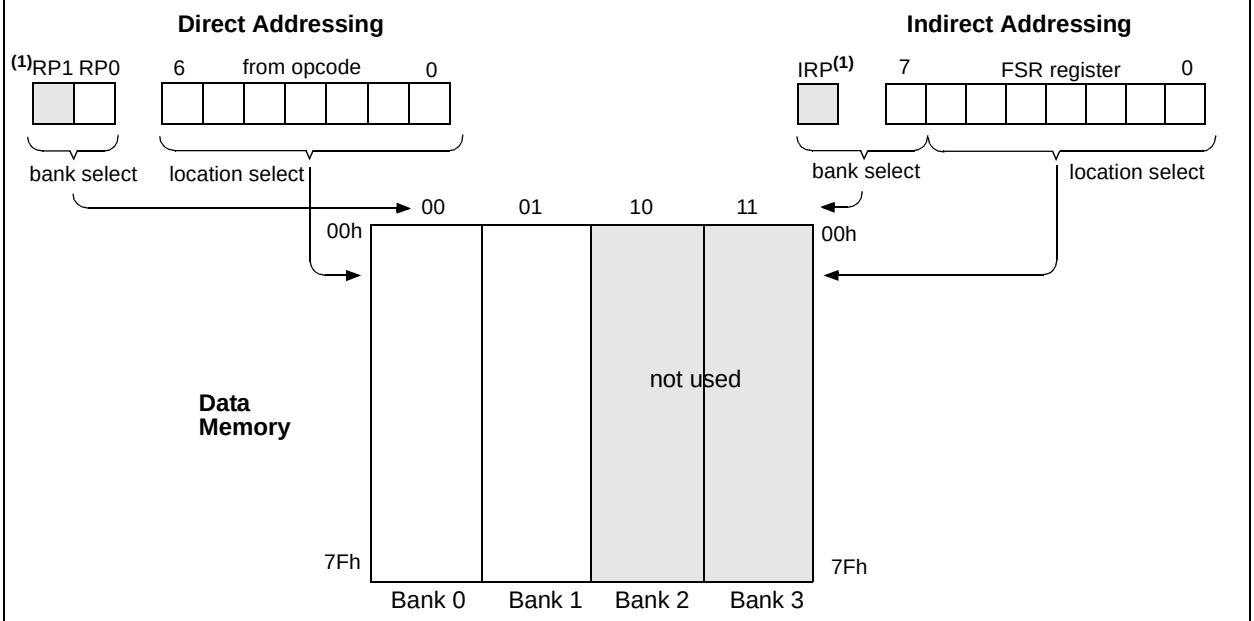
FIGURE 4-7: DIRECT/INDIRECT ADDRESSING PIC16C55X



For memory map detail see Figure 4-3 and Figure 4-5.

Note 1: The RP1 and IRP bits are reserved, always maintain these bits clear.

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TABLE 5-1: PORTA FUNCTIONS

Name	Bit #	Buffer Type	Function
RA0	Bit 0	ST	Bi-directional I/O port.
RA1	Bit 1	ST	Bi-directional I/O port.
RA2	Bit 2	ST	Bi-directional I/O port.
RA3	Bit 3	ST	Bi-directional I/O port.
RA4/T0CKI	Bit 4	ST	Bi-directional I/O port or external clock input for TMR0. Output is open drain type.

Legend: ST = Schmitt Trigger input

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
05h	PORTA	—	—	—	RA4	RA3	RA2	RA1	RA0	---x xxxx	---u uuuu
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: — = Unimplemented locations, read as '0', x = unknown, u = unchanged

Note 1: Shaded bits are not used by PORTA.

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6.2 Oscillator Configurations

6.2.1 OSCILLATOR TYPES

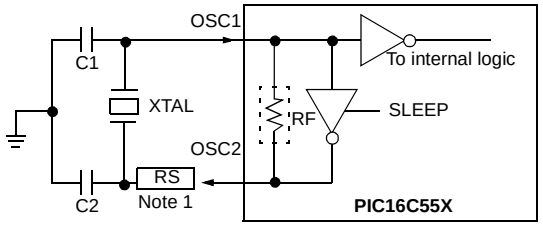
The PIC16C55X can be operated in four different oscillator options. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

6.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (Figure 6-1). The PIC16C55X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (Figure 6-2).

FIGURE 6-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



Note 1: A series resistor may be required for AT strip cut crystals.
2: See Table 6-1 and Table 6-2 for recommended values of C1 and C2.

FIGURE 6-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

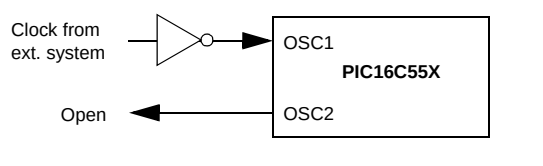


TABLE 6-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS (PRELIMINARY)

Ranges Characterized:			
Mode	**Freq**	**OSC1(C1)**	**OSC2(C2)**
XT	455 kHz 2.0 MHz 4.0 MHz	22 - 100 pF 15 - 68 pF 15 - 68 pF	22 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult with the resonator manufacturer for appropriate values of external components.

TABLE 6-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR (PRELIMINARY)

Mode	Freq	OSC1(C1)	OSC2(C2)
LP	32 kHz 200 kHz	68 - 100 pF 15 - 30 pF	68 - 100 pF 15 - 30 pF
XT	100 kHz 2 MHz 4 MHz	68 - 150 pF 15 - 30 pF 15 - 30 pF	150 - 200 pF 15 - 30 pF 15 - 30 pF
HS	8 MHz 10 MHz 20 MHz	15 - 30 pF 15 - 30 pF 15 - 30 pF	15 - 30 pF 15 - 30 pF 15 - 30 pF

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low-drive level specification. Since each crystal has its own characteristics, the user should consult with the crystal manufacturer for appropriate values of external components.

6.5.1 RB0/INT INTERRUPT

An external interrupt on RB0/INT pin is edge triggered: either rising if INTEDG bit (OPTION<6>) is set, or falling if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The RB0/INT interrupt can wake-up the processor from SLEEP, if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See Section 6.8 for details on SLEEP and Figure 6-14 for timing of wake-up from SLEEP through RB0/INT interrupt.

6.5.2 TMR0 INTERRUPT

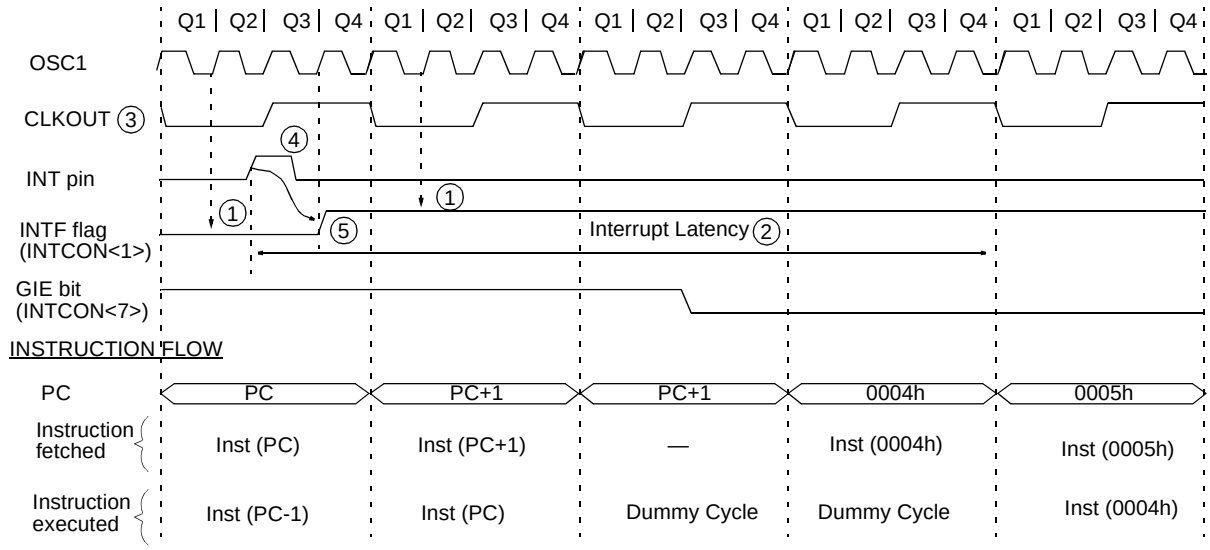
An overflow (FFh $\rightarrow$ 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can be enabled/disabled by setting/clearing T0IE (INTCON<5>) bit. For operation of the Timer0 module, see Section 7.0.

6.5.3 PORTB INTERRUPT

An input change on PORTB <7:4> sets the RBIF (INTCON<0>) bit. The interrupt can be enabled/disabled by setting/clearing the RBIE (INTCON<4>) bit. For operation of PORTB (Section 5.2).

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may get set.

FIGURE 6-12: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Interrupt latency = 3-4 TCY where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT is available only in RC Oscillator mode.

4: For minimum width of INT pulse, refer to AC specs.

5: INTF is enabled to be set anytime during the Q4-Q1 cycles.

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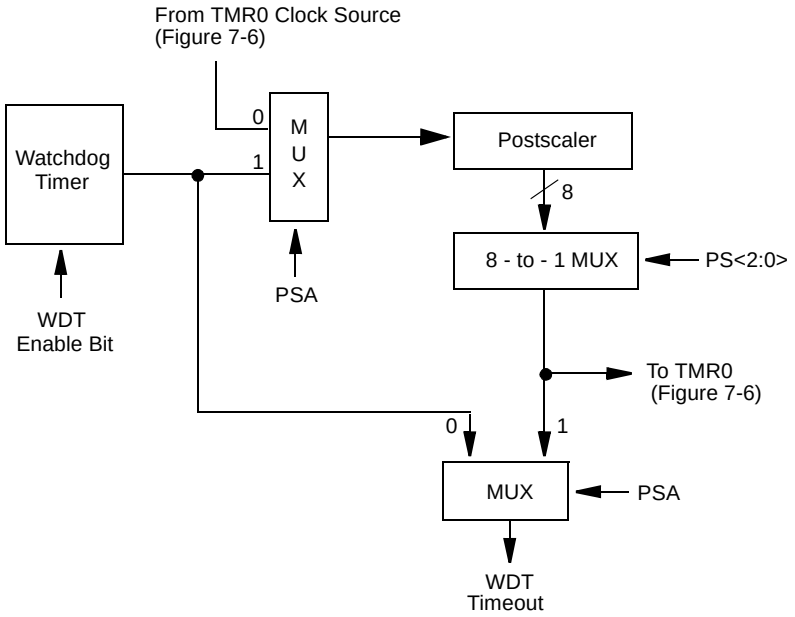
FIGURE 6-13: WATCHDOG TIMER BLOCK DIAGRAM



Note 1: T0SE, T0CS, PSA, PS0-PS2 are bits in the OPTION register.

TABLE 6-7: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on all other RESETS
2007h	Config. bits	—	Reserved	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0		
81h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged, q = value depends on condition, — = unimplemented, read as '0'.
Shaded cells are not used by the Watchdog Timer.

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6.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{PD}$ bit in the STATUS register is cleared, the $\overline{TO}$ bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at V_{DD}, or V_{SS}, with no external circuitry drawing current from the I/O pin. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level (V_{IHMC}).

Note:	It should be noted that a RESET generated by a WDT timeout does not drive $\overline{MCLR}$ pin low.

6.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on $\overline{MCLR}$ pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin or RB Port change

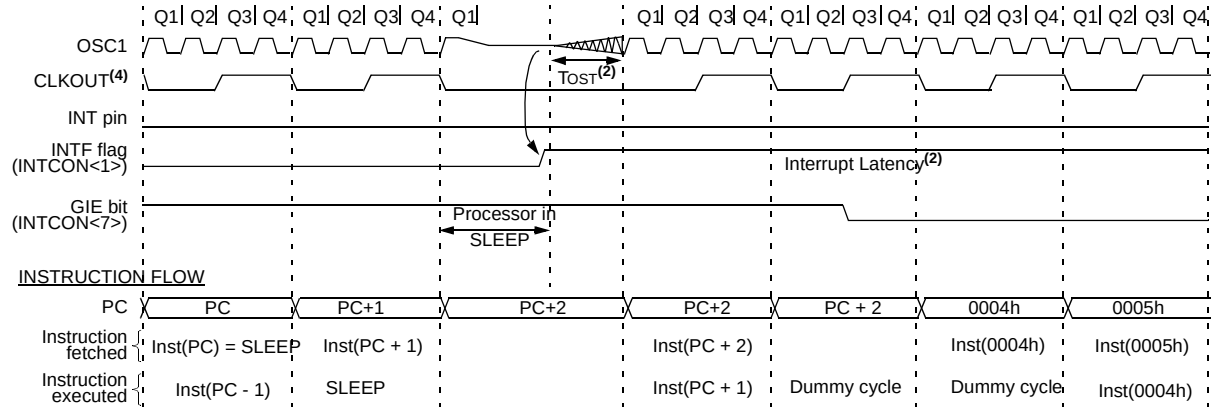
The first event will cause a device RESET. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device RESET. $\overline{PD}$ bit, which is set on power-up is cleared when SLEEP is invoked. $\overline{TO}$ bit is cleared if WDT Wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note:	If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from SLEEP. The SLEEP instruction is completely executed.

The WDT is cleared when the device wakes-up from SLEEP, regardless of the source of wake-up.

FIGURE 6-14: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP Oscillator mode assumed.
2: TOST = 1024TOSC (drawing not to scale). This delay will not be there for RC osc mode.
3: GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

NOTES:

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MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Encoding:

00	1000	dfff	ffff

Description: The contents of register f is moved to a destination dependant upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example
```
MOVF    FSR,   0
```
After Instruction
W = value in FSR register
Z = 1

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 127$

Operation: (W) → (f)

Status Affected: None

Encoding:

00	0000	1fff	ffff

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example
```
MOVWF   OPTION
```
Before Instruction
OPTION = 0xFF
W = 0x4F
After Instruction
OPTION = 0x4F
W = 0x4F

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

00	0000	0xx0	0000

Description: No operation.

Words: 1

Cycles: 1

Example
```
NOP
```

OPTION **Load Option Register**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

00	0000	0110	0010

Description: The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PIC MCU products, do not use this instruction.

NOTES:

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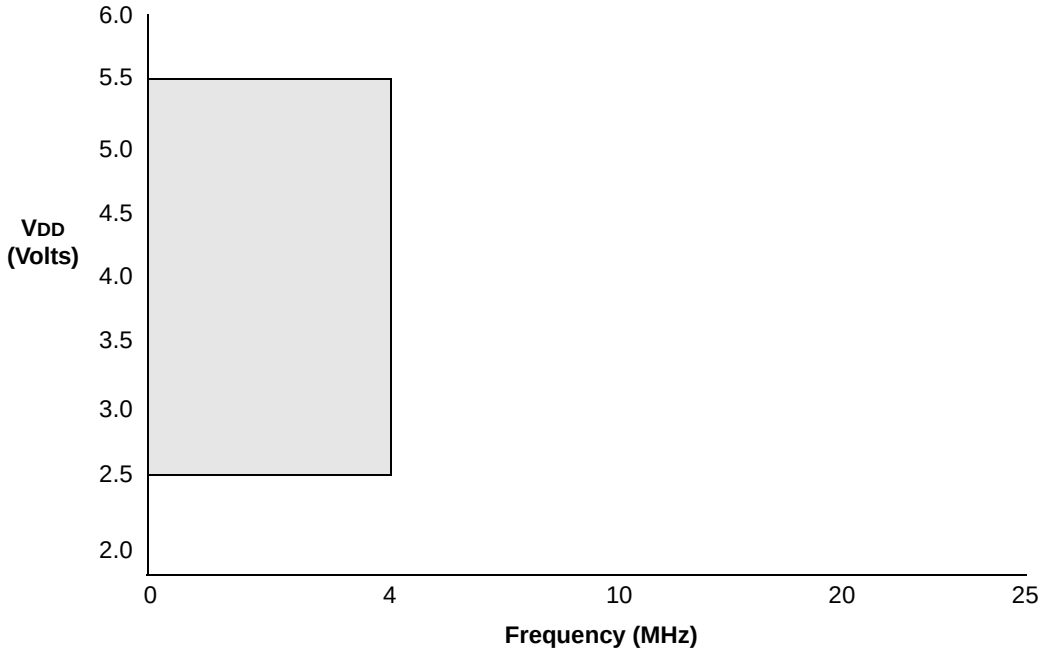
TABLE 9-1: DEVELOPMENT TOOLS FROM MICROCHIP

Category	Tool	PIC12CXXX	PIC14000	PIC16C5X	PIC16C6X	PIC16CXXX	PIC16F62X	PIC16C7X	PIC16C7XX	PIC16C8X	PIC16F8XX	PIC16C9XX	PIC17C4X	PIC17C7XX	PIC18CXX2	PIC18FXXX	24CXX/ 25CXX/ 93CXX	HCSXXX	MCRFXXX	MCP2510
Software Tools	MPLAB® Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				
Software Tools	MPLAB® C17 C Compiler												✓	✓						
Software Tools	MPLAB® C18 C Compiler														✓	✓				
Software Tools	MPASM™ Assembler/ MPLINK™ Object Linker	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Emulators	MPLAB® ICE In-Circuit Emulator	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓				
Emulators	ICEPIC™ In-Circuit Emulator	✓		✓	✓	✓		✓	✓	✓		✓								
Debugger	MPLAB® ICD In-Circuit Debugger				✓*			✓*			✓					✓				
Programmers	PICSTART® Plus Entry Level Development Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓				
Programmers	PRO MATE® II Universal Device Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Demo Boards and Eval Kits	PICDEM™ 1 Demonstration Board			✓		✓		✓†		✓			✓							
Demo Boards and Eval Kits	PICDEM™ 2 Demonstration Board				✓†			✓†							✓	✓				
Demo Boards and Eval Kits	PICDEM™ 3 Demonstration Board											✓								
Demo Boards and Eval Kits	PICDEM™ 14A Demonstration Board		✓																	
Demo Boards and Eval Kits	PICDEM™ 17 Demonstration Board													✓						
Demo Boards and Eval Kits	KEELOQ® Evaluation Kit																	✓		
Demo Boards and Eval Kits	KEELOQ® Transponder Kit																	✓		
Demo Boards and Eval Kits	microID™ Programmer's Kit																		✓	
Demo Boards and Eval Kits	125 kHz microID™ Developer's Kit																		✓	
Demo Boards and Eval Kits	125 kHz Anticollision microID™ Developer's Kit																		✓	
Demo Boards and Eval Kits	13.56 MHz Anticollision microID™ Developer's Kit																		✓	
Demo Boards and Eval Kits	MCP2510 CAN Developer's Kit																			✓

* Contact the Microchip Technology Inc. web site at www.microchip.com for information on how to use the MPLAB® ICD In-Circuit Debugger (DV164001) with PIC16C62, 63, 64, 65, 72, 73, 74, 76, 77.
** Contact Microchip Technology Inc. for availability date.
†

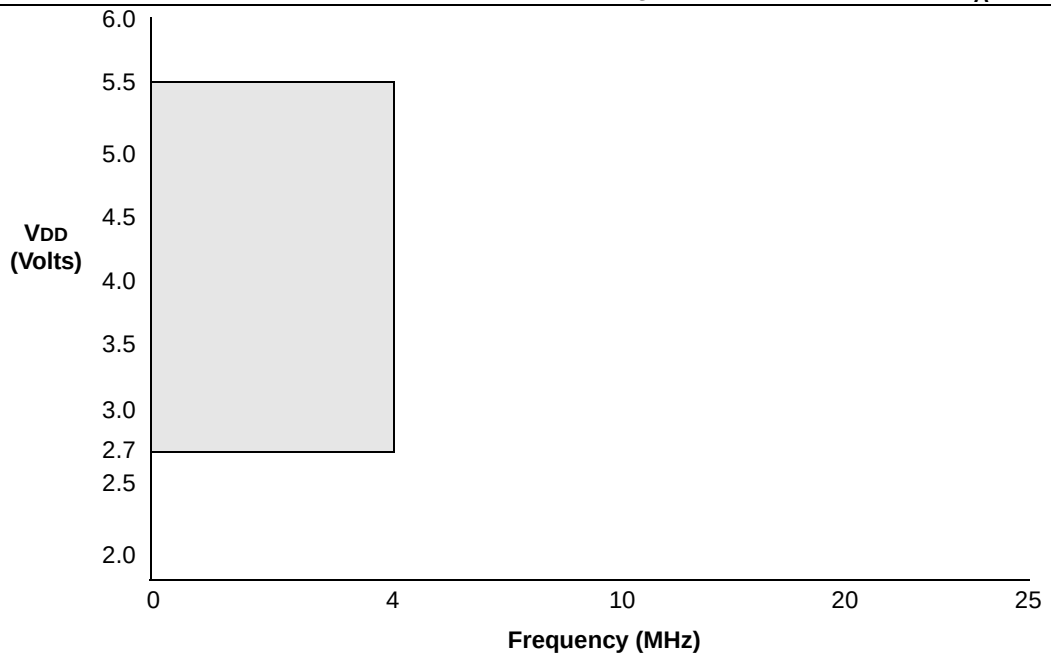
FIGURE 10-3: VOLTAGE-FREQUENCY GRAPH, 0°C ≤ T_A ≤ +85°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 10-4: PIC16LC554/557/558 VOLTAGE-FREQUENCY GRAPH, -40°C ≤ T_A ≤ 0°C



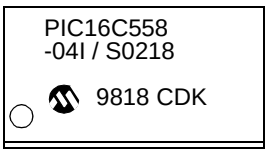
Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

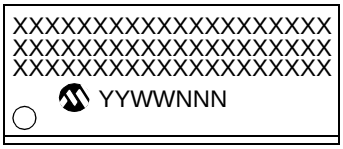
Package Marking Information (Cont'd)

18-Lead SOIC (.300")

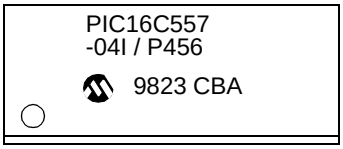
Example



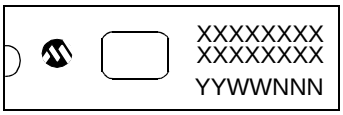
28-Lead SOIC (.300")



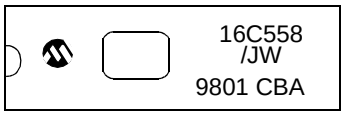
Example



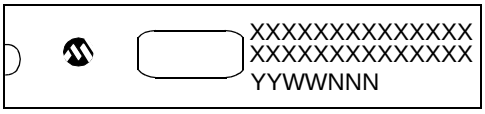
18-Lead CERDIP Windowed



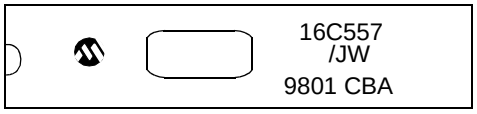
Example



28-Lead CERDIP Windowed



Example



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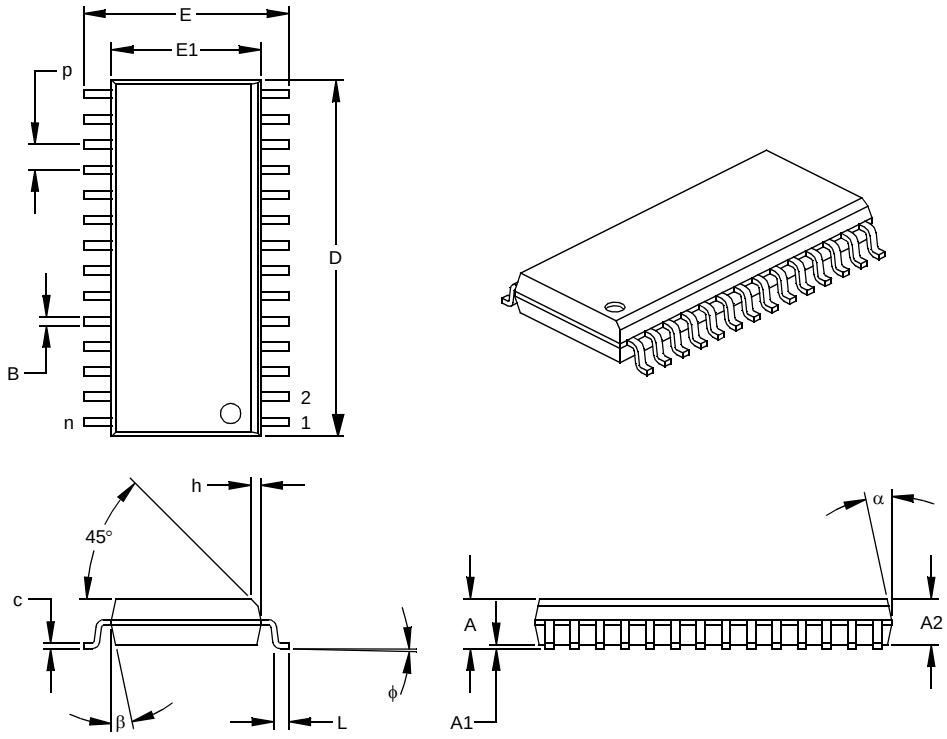
28-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	ϕ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.013	0.23	0.28	0.33
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-052

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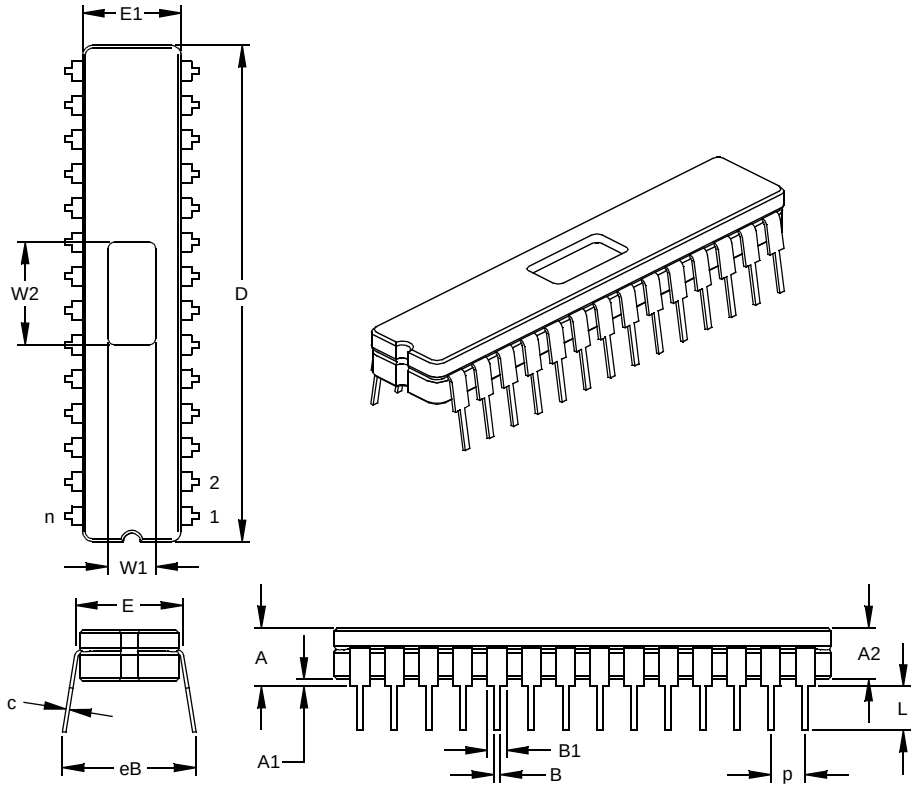
28-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	1.430	1.458	1.485	36.32	37.02	37.72
Tip to Seating Plane	L	.135	.140	.145	3.43	3.56	3.68
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.058	.065	1.27	1.46	1.65
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.290	.300	.310	7.37	7.62	7.87

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-058
Drawing No. C04-080

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NOTES:

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PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC17C756: Standard V_{DD} range PIC17C756T: (Tape and Reel) PIC17LC756: Extended V_{DD} range	
Temperature Range	- = 0°C to +70°C I = -40°C to +85°C	
Package	CL = Windowed LCC PT = TQFP L = PLCC	
Pattern	QTP, SQTP, ROM Code (factory specified) or Special Requirements. Blank for OTP and Windowed devices.	

Examples:

a) PIC17C756–16L Commercial Temp., PLCC package, 16 MHz, normal V_{DD} limits

b) PIC17LC756–08/PT Commercial Temp., TQFP package, 8MHz, extended V_{DD} limits

c) PIC17C756–33I/PT Industrial Temp., TQFP package, 33 MHz, normal V_{DD} limits

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)